



Title of Change:	Implementation of Moisture Barrier Bag Packing on ESD11B5.0ST5G and SSESD11B5.0ST5G products in accordance with MSL 3 requirements
Effective date:	02 September 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <norhayati.othman@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted.
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other Packing Change
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s) JCAP
Description and Purpose:	The change is to add Moisture Barrier Bag Packing on ESD11B5.0ST5G and SSESD11B5.0ST5G to meet customer requirement and to tally with ON Semi internal spec. The MSL level changes from 1 to 3.
List of affected Standard Parts:	ESD11B5.0ST5G SSESD11B5.0ST5G